# Octal 3-State Inverting Transciever

The MC74ACT640 octal bus transceiver is designed for asynchronous two-way communication between data buses. The device transmits data from bus  $\overline{A}$  to bus B when  $T/\overline{R} = HIGH$ , or from bus  $\overline{B}$  to bus A when  $T/\overline{R} = LOW$ . The enable input can be used to disable the device so the buses are effectively isolated.

#### **Features**

- Bidirectional Data Path
- A and B Outputs Sink 24 mA/Source -24 mA
- TTL Compatible Inputs
- These are Pb-Free Devices

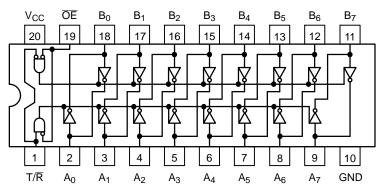


Figure 1. Pinout: 20-Lead Packages Conductors
(Top View)

### **PIN ASSIGNMENT**

PIN	FUNCTION
A <sub>0</sub> -A <sub>7</sub>	Side A Inputs or 3-State Outputs
ŌĒ	Output Enable Input
T/R	Transmit/Receive Input
B <sub>0</sub> -B <sub>7</sub>	Side B Inputs or 3-State Outputs

#### **TRUTH TABLE**

OE	T/R	Applied Inputs	Valid Direction I/P→O/P	Output
Н	Х	Х	Х	Х
L	Н	Н	$\overline{A}$ to $B$	L
L	Н	L	$\overline{A}$ to $B$	Н
L	L	Н	$\overline{B}$ to A	L
L	L	L	B to A	Н

H = HIGH Voltage Level L = LOW Voltage Level

X = Immaterial



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SOIC-20W DW SUFFIX CASE 751D

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

#### **DEVICE MARKING INFORMATION**

See general marking information in the device marking section on page 5 of this data sheet.

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V <sub>IN</sub>	DC Input Voltage (Referenced to GND)	-0.5 to V <sub>CC</sub> +0.5	V
V <sub>OUT</sub>	DC Output Voltage (Referenced to GND) (Note 1)	-0.5 to V <sub>CC</sub> +0.5	V
I <sub>IK</sub>	DC Input Diode Current	±20	mA
I <sub>OK</sub>	DC Output Diode Current	±50	mA
I <sub>OUT</sub>	DC Output Sink/Source Current	±50	mA
I <sub>CC</sub>	DC Supply Current, per Output Pin	±50	mA
I <sub>GND</sub>	DC Ground Current, per Output Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias	140	°C
$\theta_{JA}$	Thermal Resistance (Note 2)	65.8	°C/W
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 30% – 35%	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage  Human Body Model (Note 3)  Machine Model (Note 4)  Charged Device Model (Note 5)	> 2000 > 200 > 1000	V
I <sub>Latchup</sub>	Latchup Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 6)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. I<sub>OUT</sub> absolute maximum rating must be observed.
- The package thermal impedance is calculated in accordance with JESD 51-7.
- 3. Tested to EIA/JESD22-A114-A.
- 4. Tested to EIA/JESD22-A115-A.
- 5. Tested to JESD22-C101-A.
- 6. Tested to EIA/JESD78.

### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Тур	Max	Unit
V <sub>CC</sub>	DC Input Voltage (Referenced to GND)	4.5		5.5	V
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Referenced to GND)	0		V <sub>CC</sub>	V
T <sub>A</sub>	Operating Temperature, All Package Types	-40	25	+85	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time (Note 8) $ V_{CC} = 4.5 \text{ V} $ $ V_{CC} = 5.5 \text{ V} $	0 0	10 8.0	10 8.0	ns/V
I <sub>OH</sub>	Output Current – High			-24	mA
I <sub>OL</sub>	Output Current – Low			24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

7. Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.

- 8. V<sub>in</sub> from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

# **DC CHARACTERISTICS**

		V <sub>CC</sub>	T <sub>A</sub> = -	₊25°C	T <sub>A</sub> = -40°C to +85°C		
Symbol	Parameter	(V)	Тур	Guaranteed Limits		Unit	Conditions
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8 0.8	0.8 0.8	V V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V V	I <sub>OUT</sub> = -50 μA
		4.5 5.5		3.86 4.86	3.76 4.76	V V	$^*$ V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> $-24$ mA $^-$ 24 mA
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V V	I <sub>OUT</sub> = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	V V	$^*$ V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> $-24$ mA $^-$ 24 mA
I <sub>IN</sub>	Maximum Input Leakage Current	5.5		±0.1	±1.0	μΑ	$V_I = V_{CC}$ , GND
$\Delta I_{CCT}$	Additional Max. I <sub>CC</sub> /Input	5.5	0.6		1.5	mA	$V_{I} = V_{CC} - 2.1 \text{ V}$
I <sub>OZ</sub>	Maximum 3–State Current	5.5		±0.5	±5.0	μΑ	$ \begin{array}{c} V_{I}\left(OE\right) = V_{IL},V_{IH} \\ V_{I} = V_{CC},GND \\ V_{O} = V_{CC},GND \end{array} $
I <sub>OLD</sub> I <sub>OHD</sub>	†Minimum Dynamic Output Current	5.5 5.5			75 –75	mA mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5		8.0	80	μΑ	V <sub>IN</sub> = V <sub>CC</sub> or GND

<sup>\*</sup>All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

# **AC CHARACTERISTICS** $t_r = t_f = 3.0$ ns (For Figures and Waveforms, See Figures 2 and 3.)

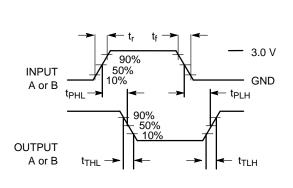
			V <sub>CC</sub> *	T <sub>A</sub> = -	⊦25°C 50 pF	T <sub>A</sub> = -40°C C <sub>L</sub> = 5	C to +85°C 50 pF	
Symbol	Para	ameter	(V)	Min	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay	An to Bn or Bn to An	5.0	1.5	8.0	1.0	8.5	ns
t <sub>PHL</sub>	Propagation Delay	An to Bn or Bn to An	5.0	1.5	8.0	1.0	9.0	ns
t <sub>PZH</sub>	Output Enable Time	OE to An or Bn	5.0	1.5	10.0	1.0	11.0	ns
t <sub>PZL</sub>	Output Enable Time	OE to An or Bn	5.0	1.5	10.0	1.0	11.0	ns
t <sub>PHZ</sub>	Output Disable Time	T/R or OE to An or Bn	5.0	1.5	10.0	1.0	11.0	ns
t <sub>PLZ</sub>	Output Disable Time	T/R or OE to An or Bn	5.0	1.5	10.0	1.0	11.0	ns

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V ±0.5 V

# **CAPACITANCE**

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>I/O</sub>	Input/Output Capacitance	15	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	45	pF	V <sub>CC</sub> = 5.0 V

# **SWITCHING WAVEFORMS**



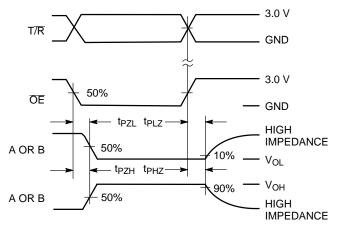
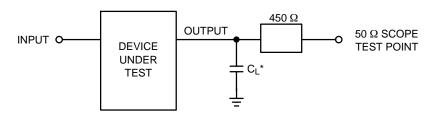


Figure 2.

Figure 3.



\*Includes all probe and jig capacitance

Figure 4. Test Circuit

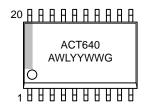
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74ACT640DWG	SOIC-20 (Pb-Free)	38 Units / Rail
MC74ACT640DWR2G	SOIC-20 (Pb-Free)	1000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# **MARKING DIAGRAMS**

SOIC-20W



A = Assembly Location

 $\begin{array}{ll} WL &= Wafer\ Lot \\ YY,\ Y &= Year \\ WW &= Work\ Week \\ G &= Pb-Free\ Package \end{array}$ 

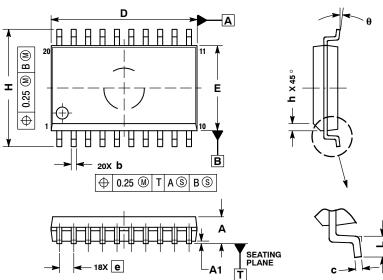




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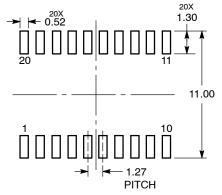




- DIMENSIONS ARE IN MILLIMETERS.
   INTERPRET DIMENSIONS AND TOLERANCES.
- PER ASME Y14.5M, 1994.
  3. DIMENSIONS D AND E DO NOT INCLUDE MOLD
- PROTRUSION.
  MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
- DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL

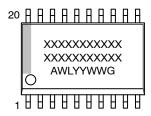
	MILLIMETERS					
DIM	MIN	MAX				
Α	2.35	2.65				
A1	0.10	0.25				
b	0.35	0.49				
С	0.23	0.32				
D	12.65	12.95				
E	7.40	7.60				
е	1.27	BSC				
Н	10.05	10.55				
h	0.25	0.75				
L	0.50	0.90				
A	0 °	7 °				

#### **RECOMMENDED SOLDERING FOOTPRINT\***



DIMENSIONS: MILLIMETERS

# **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code = Assembly Location

WL = Wafer Lot ΥY = Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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